

MAR 02 2009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Dingwei Lu	Examiner:	Jermie Cozart
Serial No.:	10/519,896	Group Art Unit:	3726
Filed:	01/31/2005	Date:	03/02/2009
Customer No.:	28862	Docket No.:	CNIP-B-PCT-US

For: **A MOULDING PROCESS OF COMPOSITE MATERIAL INCLUDING  
HIGH-THERMAL CONDUCTOR AND ROOM-TEMPERATURE  
MAGNETIC REFRIGERANT**

**Mail Stop AMENDMENT**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATION OF FACSIMILE TRANSMISSION**

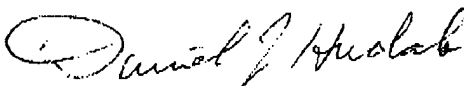
**(Facsimile: No. 1-571-273-8300 – Pages 3)**

Sir:

The undersigned hereby certifies that the attached **APPLICANT'S STATEMENT OF SUBSTANCE OF THE INTERVIEW** is being transmitted herewith via facsimile to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313, on **March 2, 2009**

Respectfully submitted,

HUDAK, SHUNK & FARINE CO. LPA

  
By: Daniel J. Hudak  
Registration No. 25,879

DJH/lb  
HUDAK, SHUNK & FARINE CO. LPA  
2020 Front Street, Suite 307  
Cuyahoga Falls, Ohio, 44221  
Telephone: (330)535-2220

RECEIVED  
CENTRAL FAX CENTER

MAR 02 2009

## IN THE UNITED STATES PATENT &amp; TRADEMARK OFFICE

Applicant:	Dingwei Lu	Examiner:	Jermie Cozart
Serial No.:	10/519,896	Group Art Unit:	3726
Filed:	01/31/2005	Date:	03/02/2009
Customer No.:	28862	Docket No.:	CNIP-B-PCT-US

For: **A MOULDING PROCESS OF COMPOSITE MATERIAL INCLUDING  
HIGH-THERMAL CONDUCTOR AND ROOM-TEMPERATURE  
MAGNETIC REFRIGERANT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**APPLICANT'S STATEMENT OF SUBSTANCE OF THE INTERVIEW**

Sir:

As required by 37 CFR §1.133(b), Applicant submits a Statement of the Substance of the Interview of February 5, 2009. During the Interview with the Examiner, as noted in the Interview Summary Report of the Examiner dated February 9, 2009, the Examiner did note that the undersigned did argue that the Wada reference was not pertinent inasmuch as it did not disclose room temperature refrigerant material or high temperature conductor material being processed into particles, sheets or filaments having a minimum size of from 0.001 mm to 0.1 mm.

The Examiner further argued that the above-noted range was not supported by the specification with regard to either the high temperature conductor or with regard to the refrigerant material.

During the course of the interview, the undersigned argued that the center paragraph of page 4 of the application stated that the minimum size of the magnetic refrigerant material balls or particles could be more than 0.001 mm. With regard to the filament size, the same range is set forth in Paragraph "5" on page 5. It is further noted that original claim 2 sets forth that the size of the refrigerant material of either the particles, sheets, or filaments could be of a size more than 0.001 mm. Thus, support for the low range of the magnetic refrigerant material does exist in the application as filed.

MAR 02 2009

With regard to the upper end of the range, that is magnetic materials having a size up to 0.1 mm, the second to the last paragraph of page 5 states that sheets can be of a size less than 0.1 mm, and the last paragraph on page 6 states that the thickness of the sheet or diameter of the filament is not more than 0.1 mm.


With respect to the thermal conductive material that the size of particles and filaments is greater than 0.001 mm, support exists on page 4, center paragraph, the end of paragraph "1" on page 4, and in paragraph 5. That the size of the sheet is less than 0.1 mm is set forth on the second to the last paragraph of page 5 as well as in original claims 7 and 9.

Although the application as filed has basis of support for at least the above-indicated materials, the same is now rendered moot inasmuch as the Applicant has amended independent claim 1 and added new independent claim 13 wherein the size of the material is stated to be greater than 0.001 mm and smaller than 1 mm.

The Applicant wishes to thank the Examiners for the courtesy of granting an interview to Applicant's representative.

Respectfully submitted,

HUDAK, SHUNK & FARINE CO. LPA



By: Daniel J. Hudak

Registration No. 25,879

DJH/lb  
2020 Front Street  
Suite 307  
Cuyahoga Falls, OH 44221-3257  
(330) 535-2220  
Attorney Docket No.: CNIP-B-PCT-US